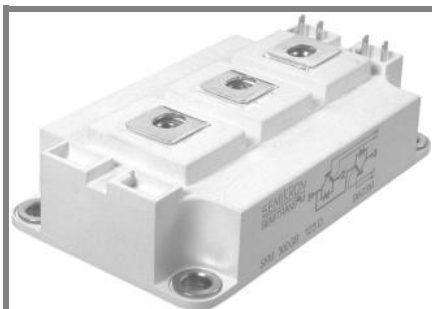


SKM 150GB12T4G



SEMITRANS® 3

IGBT4 Modules

SKM 150GB12T4G

Target Data

Features

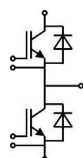
- IGBT4 = 4. Generation (Trench) IGBT
- V_{CEsat} with positive temperature coefficient
- High short circuit capability, self limiting to $6 \times I_{CNOM}$
- Soft switching 4. Generation CAL diode (CAL4)

Typical Applications

- AC inverter drives
- UPS
- Electronic welders at f_{sw} up to 20 kHz

Remarks

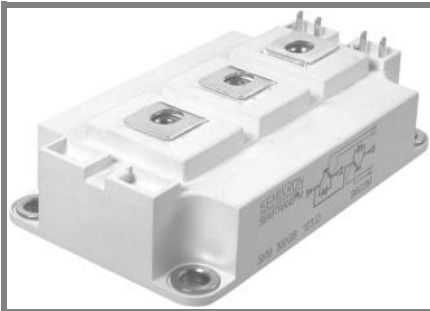
- Case temperature limited to $T_c = 125^\circ\text{C}$ max, recomm. $T_{op} = -40 \dots +150^\circ\text{C}$, product rel. results valid for $T_j \leq 150^\circ$



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Absolute Maximum Ratings		$T_c = 25^\circ\text{C}$, unless otherwise specified			
Symbol	Conditions	Values			Units
IGBT					
V_{CES}	$T_j = 25^\circ\text{C}$	1200			V
I_C	$T_j = 175^\circ\text{C}$	$T_{case} = 25^\circ\text{C}$	220		A
		$T_{case} = 80^\circ\text{C}$	170		A
I_{CRM}	$I_{CRM} = 3 \times I_{CNOM}$	450			A
V_{GES}		± 20			V
t_{psc}	$V_{CC} = 600\text{V}; V_{GE} \leq 15\text{V}; T_j = 150^\circ\text{C}$ $V_{CES} < 1200\text{V}$	10			μs
Inverse Diode					
I_F	$T_j = 175^\circ\text{C}$	$T_{case} = 25^\circ\text{C}$	180		A
		$T_{case} = 80^\circ\text{C}$	135		A
I_{FRM}	$I_{FRM} = 3 \times I_{FNOM}$	450			A
I_{FSM}	$t_p = 10\text{ms}; \text{sin.}$	$T_j = 175^\circ\text{C}$	860		A
Module					
$I_{t(RMS)}$		500			A
T_{vj}		-40 ... +175			$^\circ\text{C}$
T_{stg}		-40 ... +125			$^\circ\text{C}$
V_{isol}	AC, 1 min.	4000			V

Characteristics		$T_c = 25^\circ\text{C}$, unless otherwise specified			
Symbol	Conditions	min.	typ.	max.	Units
IGBT					
$V_{GE(th)}$	$V_{GE} = V_{CE}, I_C = 6\text{mA}$	5	5,8	6,5	V
I_{CES}	$V_{GE} = 0\text{V}, V_{CE} = V_{CES}$				mA
V_{CE0}		$T_j = 25^\circ\text{C}$	0,8	0,9	V
		$T_j = 150^\circ\text{C}$	0,7	0,8	V
r_{CE}	$V_{GE} = 15\text{V}$	$T_j = 25^\circ\text{C}$			$\text{m}\Omega$
		$T_j = 150^\circ\text{C}$			$\text{m}\Omega$
$V_{CE(sat)}$	$I_{Cnom} = 150\text{A}, V_{GE} = 15\text{V}$	$T_j = 25^\circ\text{C}_{chiplev.}$	1,85	2,05	V
		$T_j = 150^\circ\text{C}_{chiplev.}$	2,25	2,45	V
C_{res}	$V_{CE} = 25, V_{GE} = 0\text{V}$	$f = 1\text{MHz}$	9,3		nF
C_{oes}			0,58		nF
C_{res}			0,51		nF
Q_G	$V_{GE} = -8\text{V} / +15\text{V}$		850		nC
R_{Gint}	$T_j = 25^\circ\text{C}$		5		Ω
$t_{d(on)}$	$R_{Gon} = \Omega$	$V_{CC} = 600\text{V}$ $I_{Cnom} = 150\text{A}$ $T_j = 150^\circ\text{C}$ $V_{GE} = \pm 15\text{V}$			ns
t_r					ns
E_{on}	$R_{Goff} = \Omega$		14,8		mJ
$t_{d(off)}$					ns
t_f					ns
E_{off}			14,8		mJ
$R_{th(j-c)}$			per IGBT	0,2	



SEMITRANS® 3

IGBT4 Modules

SKM 150GB12T4G

Target Data

Features

- IGBT4 = 4. Generation (Trench) IGBT
- V_{CEsat} with positive temperature coefficient
- High short circuit capability, self limiting to $6 \times I_{CNOM}$
- Soft switching 4. Generation CAL diode (CAL4)

Typical Applications

- AC inverter drives
- UPS
- Electronic welders at f_{sw} up to 20 kHz

Remarks

- Case temperature limited to $T_c = 125^\circ\text{C}$ max, recomm. $T_{op} = -40 \dots +150^\circ\text{C}$, product rel. results valid for $T_j \leq 150^\circ$

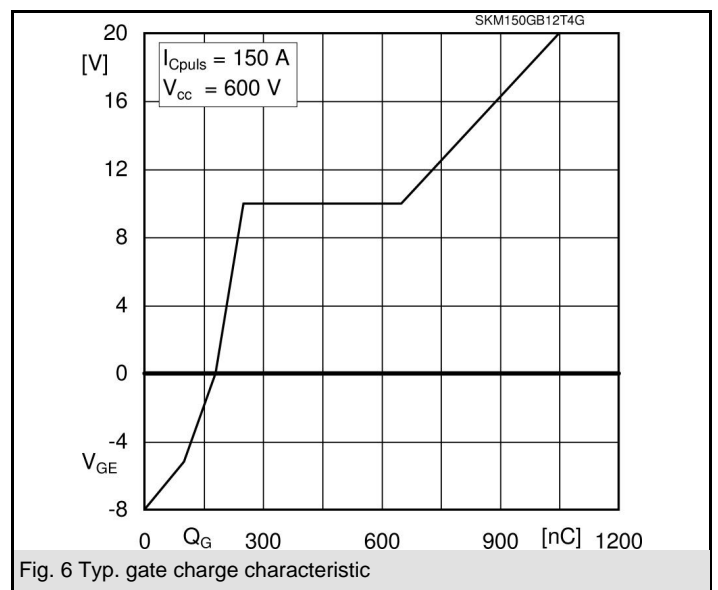
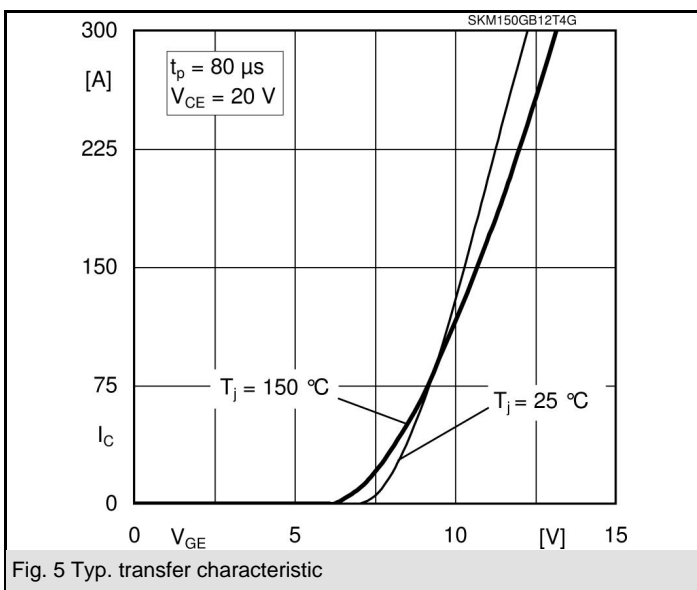
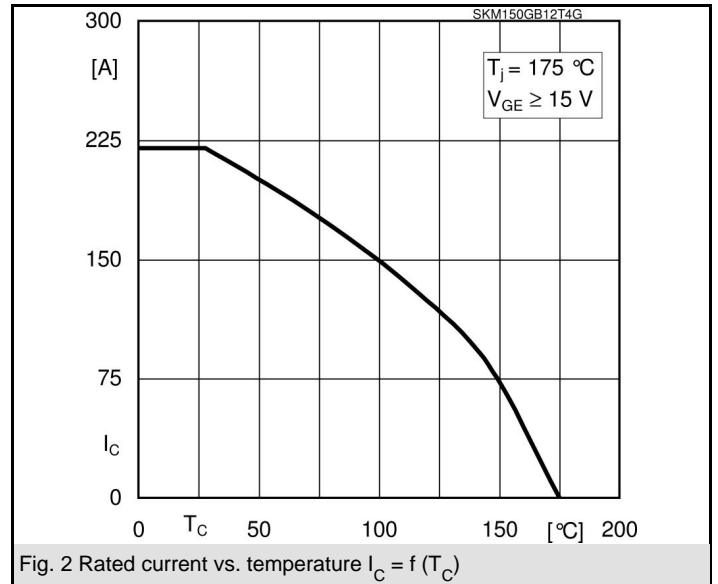
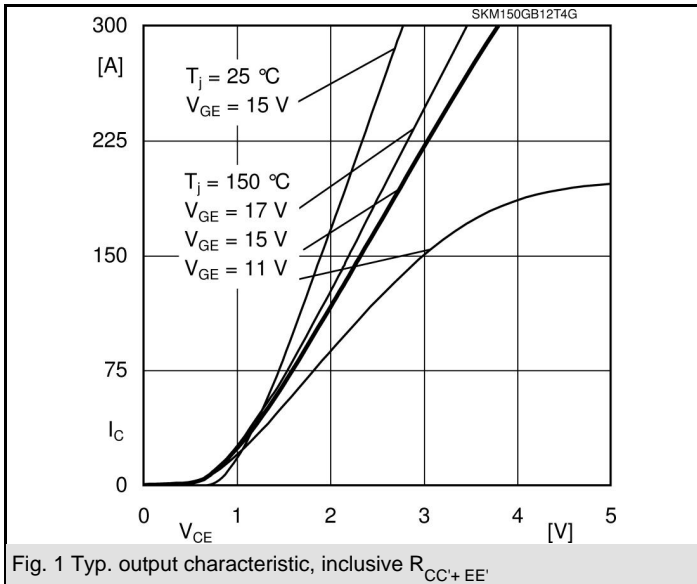


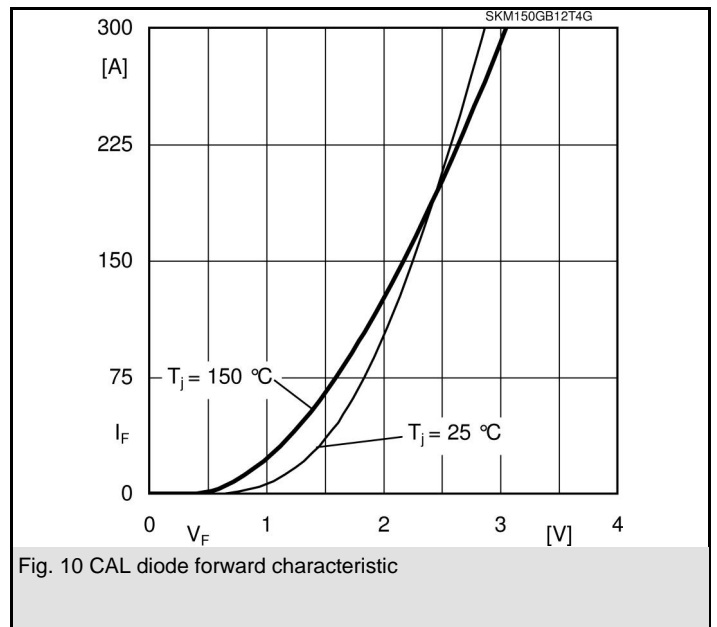
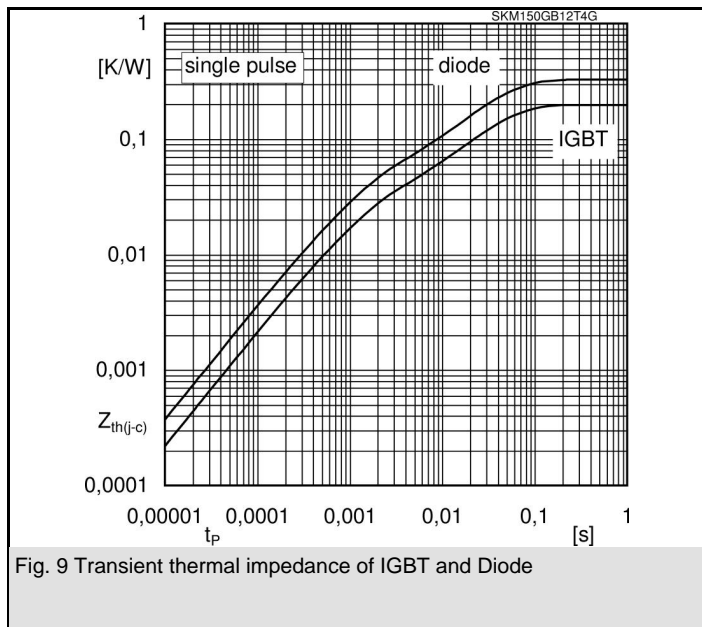
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Characteristics			min.	typ.	max.	Units
Symbol	Conditions					
Inverse Diode						
$V_F = V_{EC}$	$I_{Fnom} = 150 \text{ A}; V_{GE} = 0 \text{ V}$	$T_j = 25^\circ\text{C}_{chiplev.}$		2,2	2,5	V
		$T_j = 150^\circ\text{C}_{chiplev.}$		2,1	2,45	V
V_{F0}		$T_j = 25^\circ\text{C}$		1,3	1,5	V
		$T_j = 150^\circ\text{C}$		0,9	1,1	V
r_F		$T_j = 25^\circ\text{C}$		6	6,67	mΩ
		$T_j = 150^\circ\text{C}$		8	9	mΩ
I_{RRM}	$I_{Fnom} = 150 \text{ A}$	$T_j = 150^\circ\text{C}$				A
Q_{rr}						μC
E_{rr}	$V_{GE} = -15\text{V}$			11,3		mJ
$R_{th(j-c)}$	per diode				0,32	K/W
Freewheeling Diode						
$V_F = V_{EC}$	$I_{Fnom} = \text{A}; V_{GE} = \text{V}$	$T_j = ^\circ\text{C}_{chiplev.}$				V
V_{F0}		$T_j = ^\circ\text{C}$				V
r_F		$T_j = ^\circ\text{C}$				V
I_{RRM}	$I_{Fnom} = \text{A}$	$T_j = ^\circ\text{C}$				A
Q_{rr}						μC
E_{rr}						mJ
	per diode					K/W
Module						
L_{CE}				15	20	nH
$R_{CC'+EE'}$	res., terminal-chip	$T_{case} = 25^\circ\text{C}$			0,35	mΩ
		$T_{case} = 125^\circ\text{C}$			0,5	mΩ
$R_{th(c-s)}$	per module			0,02	0,038	K/W
M_s	to heat sink M6			3	5	Nm
M_t	to terminals M6			2,5	5	Nm
w					325	g

This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX.

This technical information specifies semiconductor devices but promises no characteristics. No warranty or guarantee expressed or implied is made regarding delivery, performance or suitability.



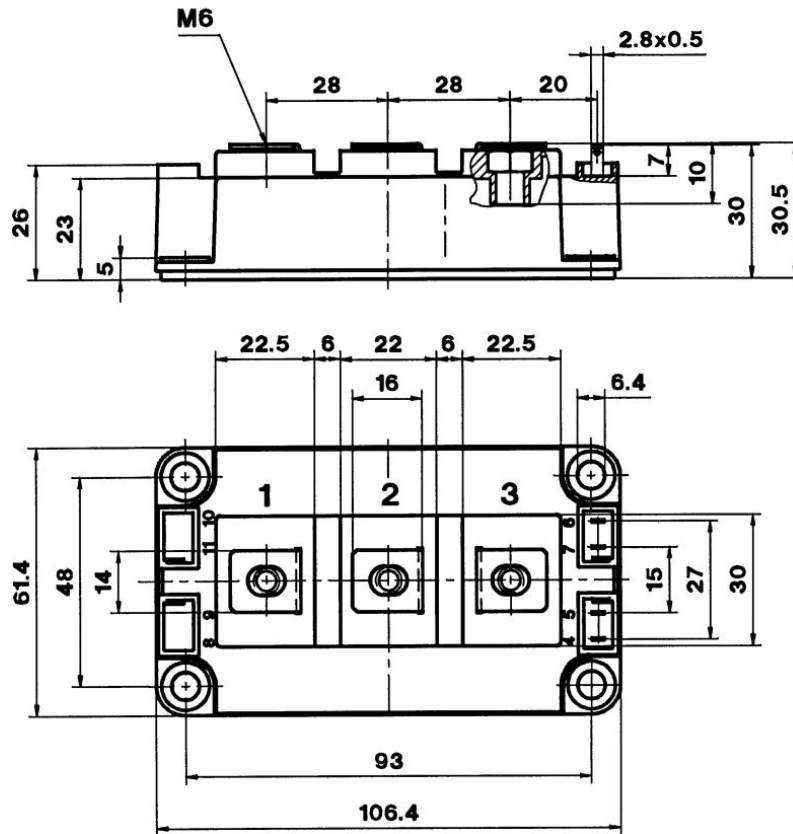


SKM 150GB12T4G

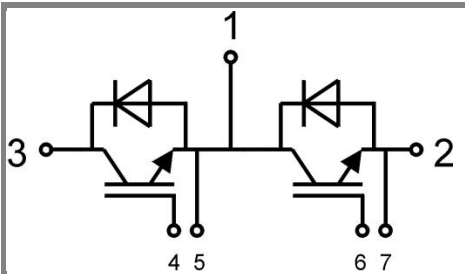
UL Recognized
File no. E 63 532

Dimensions in mm

CASED56



Case D56



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Case D56